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(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2023/0232579 A1**
(43) **Pub. Date: Jul. 20, 2023**(54) **INTEGRATED LIQUID-COOLED HEAT DISSIPATION DEVICE**(52) **U.S. Cl.**
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Dongguan City (CN)(57) **ABSTRACT**(72) Inventors: **Xiao FAN**, Dongguan City (CN);
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The present invention relates to the technical field of liquid-cooled heat dissipation, and in particular to an integrated liquid-cooled heat dissipation device. The heat dissipation device includes a first water chamber, a pumping device and a first interface. The first interface is mounted on one side of the first water chamber. The pumping device is provided in an embedded manner in the first water chamber, and the pumping device includes a water pump water chamber which is in communication with the first interface and an interior of the first water chamber. An objective of the present invention is to provide an integrated liquid-cooled heat dissipation device, which, through the rational design of a pumping device and a heat dissipation device, solves the problem that the integrated pumping and dissipation structure cannot meet the general space requirements.

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